

Sub B1
a first integrated semiconductor chip having a one side and a reverse side;
a first electrode for wiring formed on the first chip one side;
a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface;
a second integrated semiconductor chip having a one side and a reverse side, the second chip one side facing the interposer substrate first surface, the second chip being formed on the interposer substrate first surface; and
a second electrode for wiring formed on the second chip one side so as to be exposed through the interposer substrate through-hole, the second electrode to be wired through the through-hole to external terminals on the interposer substrate second surface, the first chip being formed on the second chip reverse side with the first chip reverse side facing the second chip reverse side.

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Sub B2
2. (Amended) A semiconductor chip package, comprising:
a first integrated semiconductor chip having a first chip size and having a one side and a reverse side;
a first electrode for wiring formed on the first chip one side;
a second integrated semiconductor chip having a second chip size and having a one side and a reverse side, the first chip being integrally mounted to the second chip with the second chip reverse side opposing the first chip reverse side;
a second electrode for wiring formed on the second chip one side;
a nonconductive interposer substrate having opposite first and second surfaces, and

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having a through-hole extending therethrough from the first surface to the second surface,
the through-hole being larger than the first and second chip sizes;

an adhesive sheet having opposite first and second surfaces, the adhesive sheet
being formed of a sheet-shaped adhesive material provided on the interposer substrate
at the interposer substrate first surface so as to cover the through-hole, the adhesive
sheet second surface being exposed through the through-hole from a side of the
interposer substrate at the interposer substrate second surface,

wherein the second chip reverse side is fixed the adhesive sheet second surface,
and the first chip reverse side is fixed to the adhesive sheet first surface so as to
oppose the second chip reverse side at a position at which the second chip is fixed,
whereby the second electrode can be wired to any external terminals on the interposer
substrate second surface.

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4. (Amended) A semiconductor chip package, comprising:

a first integrated semiconductor chip having a first chip size and having a one side
and a reverse side;

a first electrode for wiring formed on the first chip one side;

a second integrated semiconductor chip having a second chip size and having a one
side and a reverse side, the first chip being integrally mounted to the second chip with the
second chip reverse side opposing the first chip reverse side,

an interposer substrate through-hole being smaller than the first chip size and larger than
the second chip size,

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wherein the first chip is fixed to the interposer substrate first surface at a portion of the first chip reverse side, such that the through-hole is covered by the first chip, and

wherein the second chip reverse side is fixed to the first chip reverse side, the first chip reverse side being exposed through the through-hole from a side of the interposer substrate at the interposer substrate second surface.

4.
~~5.~~ (Amended) A semiconductor chip package according to claim 1, wherein the interposer substrate has a sunken region, which is sunken into the side of the interposer substrate at the interposer substrate second surface, and the through-hole is provided through the sunken region.

5.
~~6.~~ (Amended) A semiconductor chip package according to claim ²~~5~~, wherein the interposer substrate has, a sunken region, which is sunken into the side of the interposer substrate at the interposer substrate second surface, and the through-hole is provided through the sunken region.

6.
~~7.~~ (Amended) A semiconductor chip package according to claim ³~~6~~, wherein the interposer substrate has a sunken region, that is sunken into the side of the interposer substrate at the interposer substrate second surface, and the through-hole is provided through the sunken region.

~~7~~~~8. (Amended) A semiconductor chip package, comprising:~~

Sub B3 } a first integrated semiconductor chip having a first chip size and having a one side and a reverse side;

a first electrode for wiring formed on the first chip one side;

a second integrated semiconductor chip having a second chip size and having a one side and a reverse side, the first chip being integrally mounted to the second chip with the second chip reverse side opposing the first chip reverse side;

a second electrode for wiring formed on the second chip one side;

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cont. a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface; and

an adhesive sheet formed of sheet-shaped adhesive material at the interposer substrate first surface so as to cover the through-hole, the adhesive sheet being larger than the second chip size and having a hole smaller than the second chip size, second chip size than the second chip size,

wherein the second chip is fixed, at the second chip one side, to the interposer substrate second surface via the adhesive sheet,

wherein the first chip reverse side is fixed to the second chip reverse side, and

wherein the second chip electrode for wiring is exposed from the side of the interposer substrate at the interposer substrate second at a reverse surface side of the surface through the adhesive sheet small hole and the adhesive sheet through-hole.

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~~8~~. (Amended) A semiconductor chip package according to claim 1, wherein the interposer substrate is formed of one of nonconductive tape and a glass epoxy material.

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~~10~~. (Amended) A semiconductor chip package according to claim ²~~8~~, wherein the interposer substrate is formed of one of nonconductive tape and a glass epoxy material.

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~~11~~. (Amended) A semiconductor chip package according to claim ³~~9~~, wherein the interposer substrate is formed of one of nonconductive tape and a glass epoxy material.

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~~12~~. (Amended) A semiconductor chip package according to claim ⁹~~8~~, wherein the interposer substrate is formed of one of a nonconductive tape and a glass epoxy material.

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REMARKS

AMENDMENT

(09/912,064)